



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20130723002
TPS40200-Q1 datasheet - CMS C1307014
Information Only**

Date: 7/25/2013
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to a specification for a device that is currently offered by Texas Instruments.

This notification period is per TI's standard process. Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130723002
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS40200QDRQ1	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130723002	PCN Date:	07/25/2013
Title:	TPS40200-Q1 datasheet - CMS C1307014		
Customer Contact:	PCN Manager	Phone:	+1(214) 480-6037
Dept:	Quality Services		
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input checked="" type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>		<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

PCN Details	
Description of Change:	
Texas Instruments publication SLUS739 has changed as described below: Changes from Revision D (July 2011) to Revision E: Page 3, Deleted T _A test condition and values from Feedback voltage parameter in ELECTRICAL CHARACTERISTICS table	
Reason for Change:	
Remove redundant test condition.	
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):	
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.	
Changes to product identification resulting from this PCN:	
None	
Product Affected:	
TPS40200QDRQ1	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com